

February 1984 Revised February 1999

# MM74HCT00 Quad 2 Input NAND Gate

#### **General Description**

The MM74HCT00 is a NAND gates fabricated using advanced silicon-gate CMOS technology which provides the inherent benefits of CMOS—low quiescent power and wide power supply range. This device is input and output characteristic and pin-out compatible with standard 74LS logic families. All inputs are protected from static discharge damage by internal diodes to  $\rm V_{CC}$  and ground.

MM74HCT devices are intended to interface between TTL and NMOS components and standard CMOS devices.

These parts are also plug-in replacements for LS-TTL devices and can be used to reduce power consumption in existing designs.

#### **Features**

- TTL, LS pin-out and threshold compatible
- Fast switching: t<sub>PLH</sub>, t<sub>PHL</sub>=14 ns (typ)
- Low power: 10 µW at DC
- High fan out, 10 LS-TTL loads

## **Ordering Code:**

Order Number	Package Number	Package Description
MM74HCT00M	M14A	14-Lead Small Outline Integrate Circuit (SOIC), JEDEC MS-120, 0.150" Narrow
MM74HCT00SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
MM74HCT00MTC	MTC14	14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
MM74HCT00N	N14A	14-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

#### **Connection Diagram**

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#### **Logic Diagram**

### **Absolute Maximum Ratings**(Note 1)

(Note 2)

Supply Voltage (V<sub>CC</sub>) -0.5 to +7.0V DC Input Voltage (V<sub>IN</sub>) -1.5 to  $V_{CC}$ +1.5VDC Output Voltage (V<sub>OUT</sub>) -0.5 to  $V_{CC} + 0.5 V$ Clamp Diode Current (I<sub>IK</sub>, I<sub>OK</sub>) ±20 mA DC Output Current, per pin (I<sub>OUT</sub>) ±25 mA DC  $V_{CC}$  or GND Current, per pin ( $I_{CC}$ ) ±50 mA Storage Temperature Range ( $T_{STG}$ )  $-65^{\circ}C$  to  $+150^{\circ}C$ Power Dissipation (P<sub>D</sub>) 600 mW

(Note 3)

S.O. Package only Lead Temperature (T<sub>L</sub>)

> (Soldering 10 seconds) 260°C

### **Recommended Operating Conditions**

	Min	Max	Units
Supply Voltage (V <sub>CC</sub> )	4.5	5.5	V
DC Input or Output Voltage	0	$V_{CC}$	V
$(V_{IN}, V_{OUT})$			
Operating Temperature Range (T <sub>A</sub> )	-40	+85	°C
Input Rise or Fall Times			
$(t_r, t_f)$		500	ns

Note 1: Absolute Maximum Ratings are those values beyond which damage to the device may occur.

Note 2: Unless otherwise specified all voltages are referenced to ground. Note 3: Power Dissipation temperature derating — plastic "N" package: –

12 mW/°C from 65°C to 85°C.

#### **DC Electrical Characteristics**

 $V_{CC} = 5V \pm 10\%$  (unless otherwise specified)

Symbol	Parameter	Conditions	T <sub>A</sub> = 25°C		T <sub>A</sub> = -40 to 85°C	T <sub>A</sub> = -55 to 125°C	Units
Symbol		Conditions	Тур		Guaranteed Limits		
V <sub>IH</sub>	Minimum HIGH Level			2.0	2.0	2.0	V
	Input Voltage						
V <sub>IL</sub>	Maximum LOW Level			0.8	0.8	0.8	V
	Input Voltage						
V <sub>OH</sub>	Minimum HIGH Level	$V_{IN} = V_{IH}$ or $V_{IL}$					
	Output Voltage	$ I_{OUT} =20~\mu\text{A}$	$V_{CC}$	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	V <sub>CC</sub> -0.1	V
		$ I_{OUT}  = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$	4.2	3.98	3.84	3.7	V
		$ I_{OUT}  = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$	5.2	4.98	4.84	4.7	V
V <sub>OL</sub>	Maximum LOW Level	$V_{IN} = V_{IH}$					
	Voltage	$ I_{OUT}  = 20 \ \mu A$	0	0.1	0.1	0.1	V
		$ I_{OUT}  = 4.0 \text{ mA}, V_{CC} = 4.5 \text{V}$	0.2	0.26	0.33	0.4	V
		$ I_{OUT}  = 4.8 \text{ mA}, V_{CC} = 5.5 \text{V}$	0.2	0.26	0.33	0.4	V
I <sub>IN</sub>	Maximum Input	$V_{IN} = V_{CC}$ or GND,		±0.05	±0.5	±1.0	μΑ
	Current	$V_{IH}$ or $V_{IL}$					
I <sub>CC</sub>	Maximum Quiescent	$V_{IN} = V_{CC}$ or GND,		1.0	10	40	μΑ
	Supply Current	$I_{OUT} = 0 \mu A$					
		V <sub>IN</sub> = 2.4V or 0.5V (Note 4)	0.18	0.3	0.4	0.5	mA

500 mW

Note 4: This is measured per input with all other inputs held at V<sub>CC</sub> or ground.

### **AC Electrical Characteristics**

 $V_{CC} = 5.0V$ ,  $t_r = t_r = 6$  ns,  $C_L = 15$  pF,  $T_A = 25$ °C (unless otherwise noted)

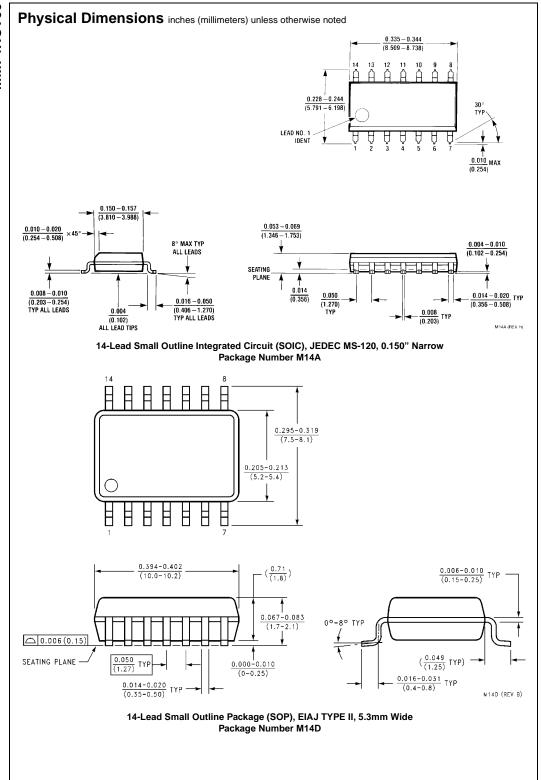
Symbol	Parameter	Conditions	Тур	Guaranteed Limit	Units
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay		14	18	ns

# **AC Electrical Characteristics**

 $V_{CC} = 5.0V \pm 10\%$ ,  $t_r = t_f = 6$  ns,  $C_L = 50$  pF (unless otherwise noted)

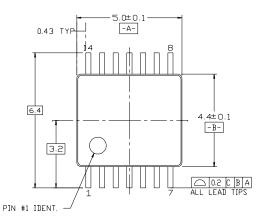
Symbol	Parameter	Conditions	T <sub>A</sub> = 25°C		$T_A = -40 \text{ to } 85^{\circ}\text{C}$ $T_A = -55 \text{ to } 125^{\circ}\text{C}$		Units
Cymbol			Тур		Guaranteed L	imits	Jillo
t <sub>PLH</sub> , t <sub>PHL</sub>	Maximum Propagation Delay		18	23	29	35	ns
t <sub>THL</sub> , t <sub>TLH</sub>	Maximum Output Rise & Fall Time		8	15	19	22	ns
C <sub>PD</sub>	Power Dissipation Capacitance	(Note 5)	30				pF
C <sub>IN</sub>	Input Capacitance		5	10	10	10	pF

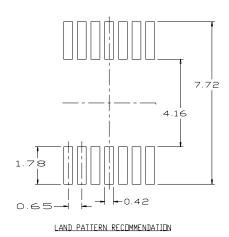
Note 5:  $C_{PD}$  determines the no load dynamic power consumption,  $P_D = C_{PD} \ V_{CC}^2 \ f + I_{CC} \ V_{CC}$ , and the no load dynamic current consumption,  $I_S = C_{PD} \ V_{CC} \ f + I_{CC}$ .

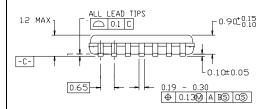


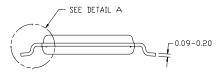
### Physical Dimensions inches (millimeters) unless otherwise noted (Continued)

14LD, TSSOP, JEDEC MO-153, 4.4MM WIDE



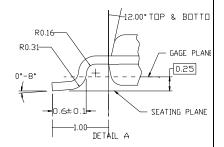






#### NOTES

- A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ABJREF NOTE 6, DATED 7/93
- B. DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS



14-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide Package Number MTC14

#### Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 0.740 - 0.770 (18.80 - 19.56)0.090 (2.286) 14 13 12 11 10 9 8 14 13 12 INDEX AREA 0.250 ± 0.010 (6.350±0.254) PIN NO. 1 IDENT PIN NO. 1 IDENT 1 2 3 4 5 6 7 1 2 3 $\frac{0.092}{(2.337)}$ DIA $\frac{0.030}{(0.762)}$ MAX OPTION 1 OPTION 02 $\frac{0.135 \pm 0.005}{(3.429 \pm 0.127)}$ 0.300 - 0.320(7.620 - 8.128) 0.065 0.145 - 0.200 0.060 (1.524) 4° TYP Optional (1.651) (3.683 - 5.080)95°±5° $\frac{0.008 - 0.016}{(0.203 - 0.406)}$ TYP 0.020 (0.508)0.125 - 0.150 $\overline{(3.175 - 3.810)}$ $\overline{(1.905 \pm 0.381)}$ 0.014-0.023 TYP (7.112)-MIN $\frac{0.100 \pm 0.010}{(2.540 \pm 0.254)} \text{ TYP}$ (0.356 - 0.584) $\frac{0.050 \pm 0.010}{(1.270 - 0.254)} \text{ TYP}$ $0.325 ^{\,+\,0.040}_{\,-\,0.015}$

14-Line Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide Package Number N14A

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8.255 + 1.016

N14A (REV.F)

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